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TECHNOLOGY CENTER R3700

ATTORNEY DOCKET NO. 025311-0115

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re patent application of

Applicant: Yashimasa KAWASE

Title: WAFER HEAT-TREATMENT SYSTEM AND WAFER HEAT-TREATMENT METHOD

Appl. No.: 10/066,783

Filing Date: February 6, 2002

Examiner: G. Wilson

Art Unit: 3749

8/A
J. Hand
2-28-03

AMENDMENT AND REPLY UNDER 37 C.F.R. § 1.111

Commissioner for Patents
Washington, D.C. 20231

Sir:

In reply to the Office Action mailed December 31, 2002, please amend the application as follows and consider the following remarks.

In the Claims:

In accordance with 37 C.F.R. § 1.121, please substitute for claim 1, the following rewritten version of the same claim, as amended. The changes are shown explicitly in the attached "Versions with Markings to Show Changes Made."

1. (Once Amended) A wafer heat-treatment system for processing a wafer by a high-temperature heat-treatment process and cooling the heat-treated wafer, said wafer heat-treatment system comprising:

walls surrounding a closed space enclosing the wafer and having a hollow sealing a gas in said walls; and

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USSN 10/066,783
Attorney Docket No. 025311-0115

A' a pressure-regulating unit connecting to said hollow for regulating pressure in said hollow.
